

وَمَا أَوْتِيْتُهُ مِنَ الْعِلْمِ إِلَّا قَلِيلًا

Analog IC Design

Lecture 01 Introduction

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Introduction



ENIAC, U.S. Army, 1946

Size → Large hall ($> 150\text{m}^2$)

Power Consumption $\approx 150\text{kW}$



Smart phone, 2017

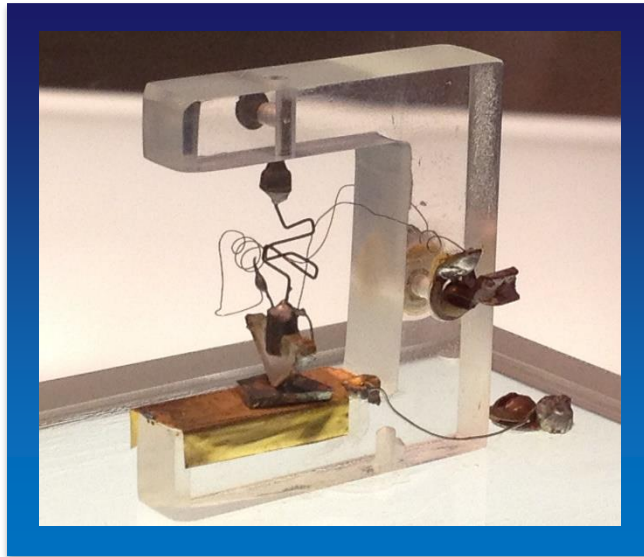
Size → Your pocket

Power consumption $< 1\text{W}$

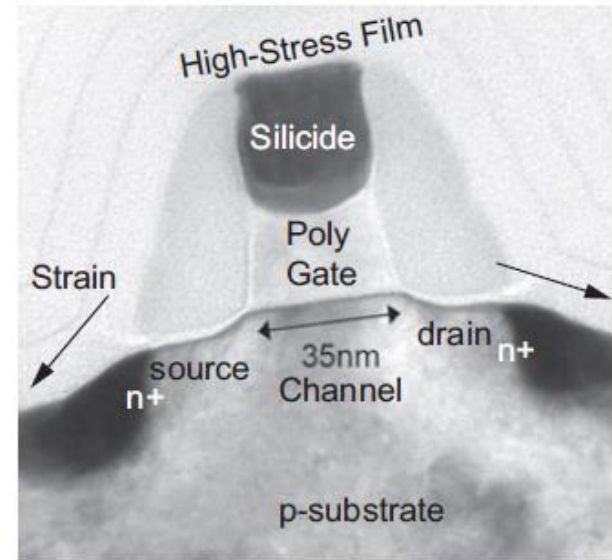
Electronics All Around Us



Transistor Evolution

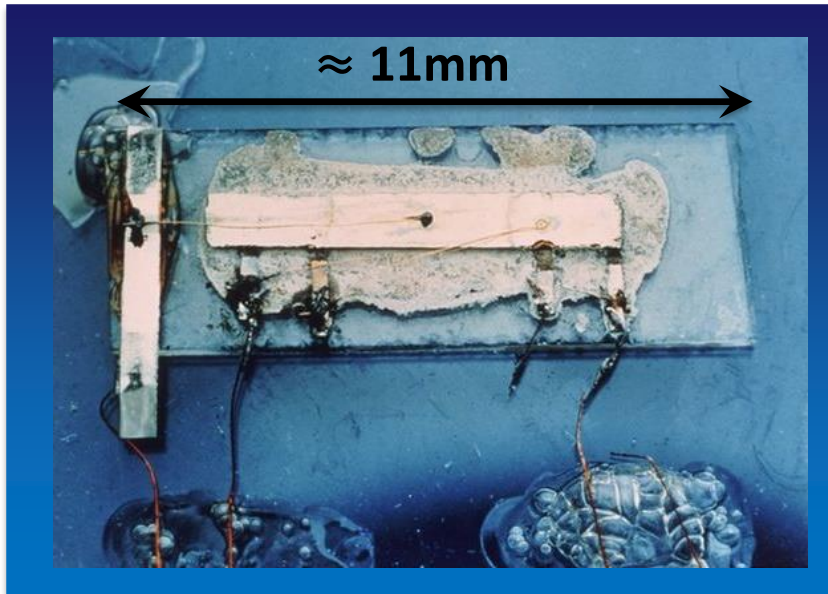


First transistor
Emitter and Collector contacts
separation $\approx 100\mu\text{m}$
Bell Labs, 1947



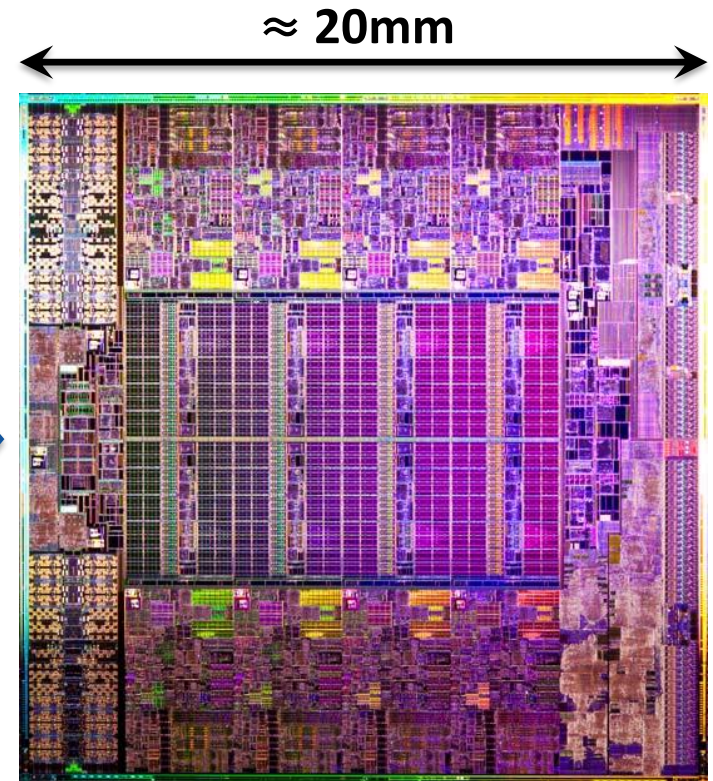
Modern MOSFET
Effective channel
length $\approx 35\text{nm}$
Intel, 2006

Integrated Circuit Evolution



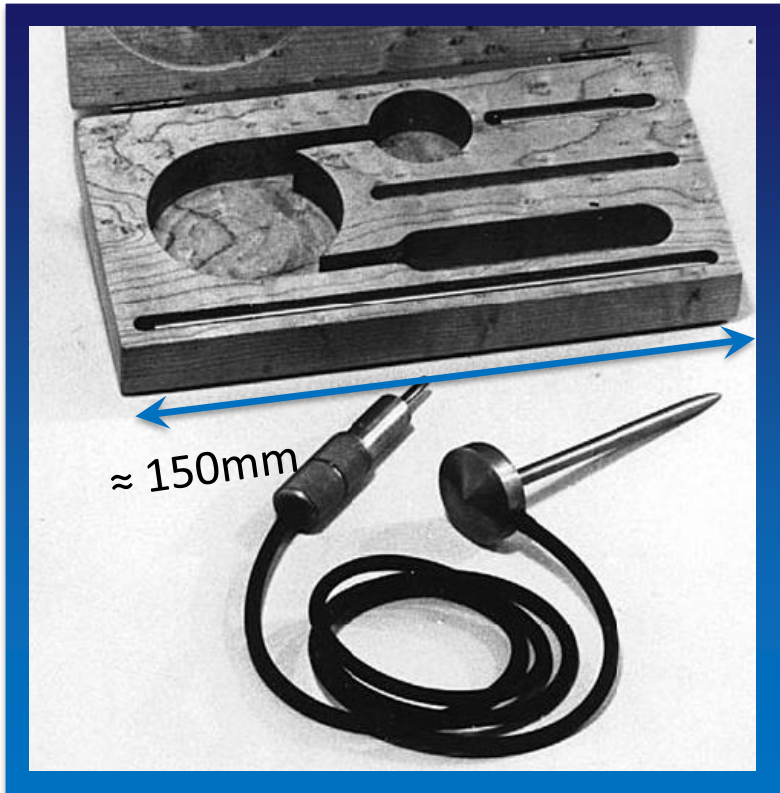
First IC

Only one transistor (+ R + C)!
Texas Instruments (TI), 1958



Xeon E5 Microprocessor
2.26 billion transistors!
Intel, 2012

Sensing Microsystems

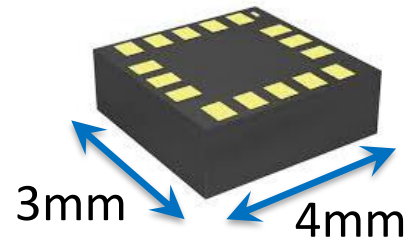


First accelerometer

B&K, 1940s

Simple bulky transducer

Acceleration → Voltage



ADXL350

Analog Devices, 2012

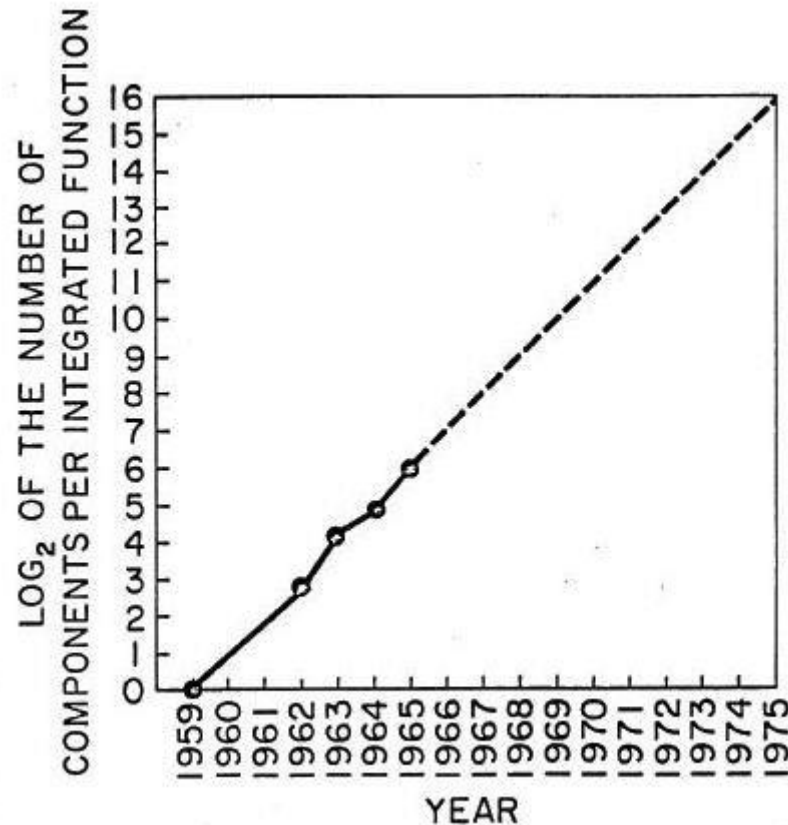
Complete system on a tiny chip

- 3-axis MEMS* accelerometer
- Interface electronics
- Analog-to-digital conversion
- Memory
- Control logic
- Power management
- Digital interface

*MEMS = Micro-Electro-Mechanical Systems

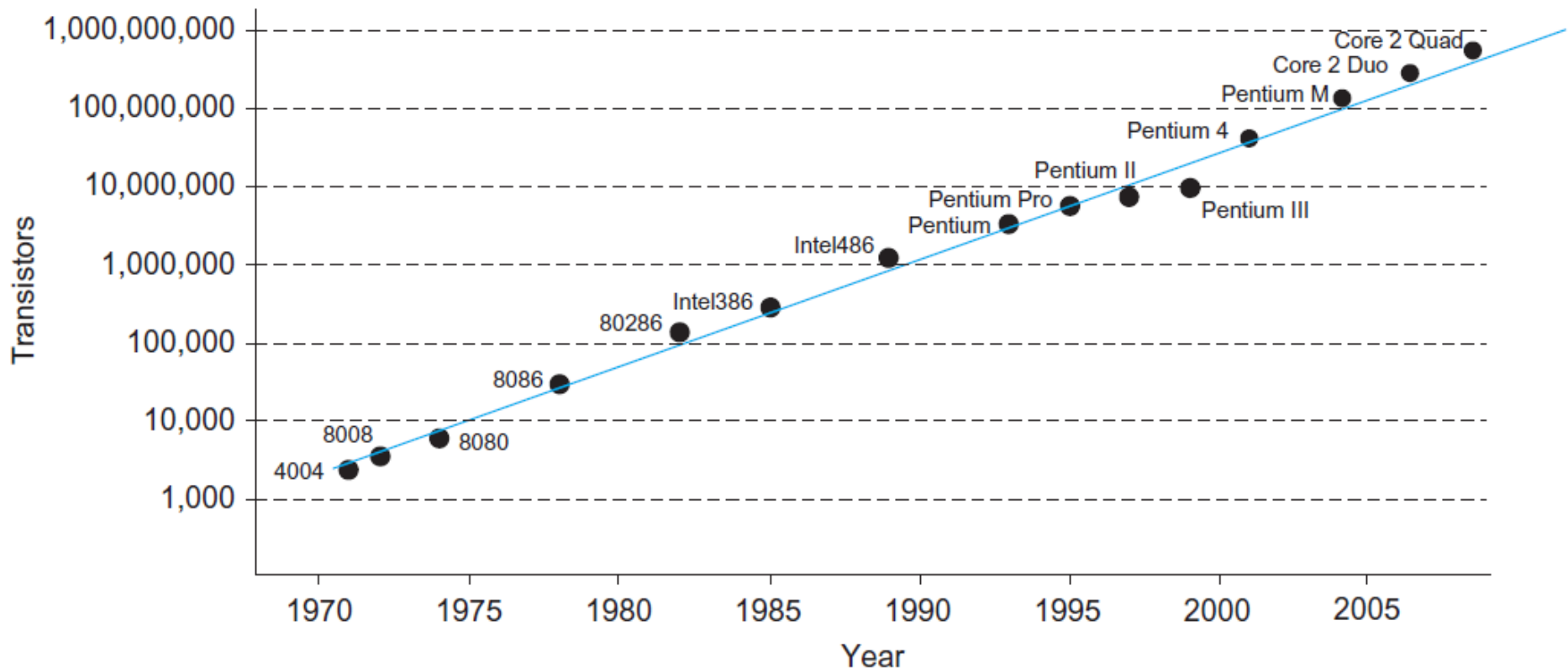
Moore's Law

- ❑ Moore's law [1965]: Transistor count doubles every year



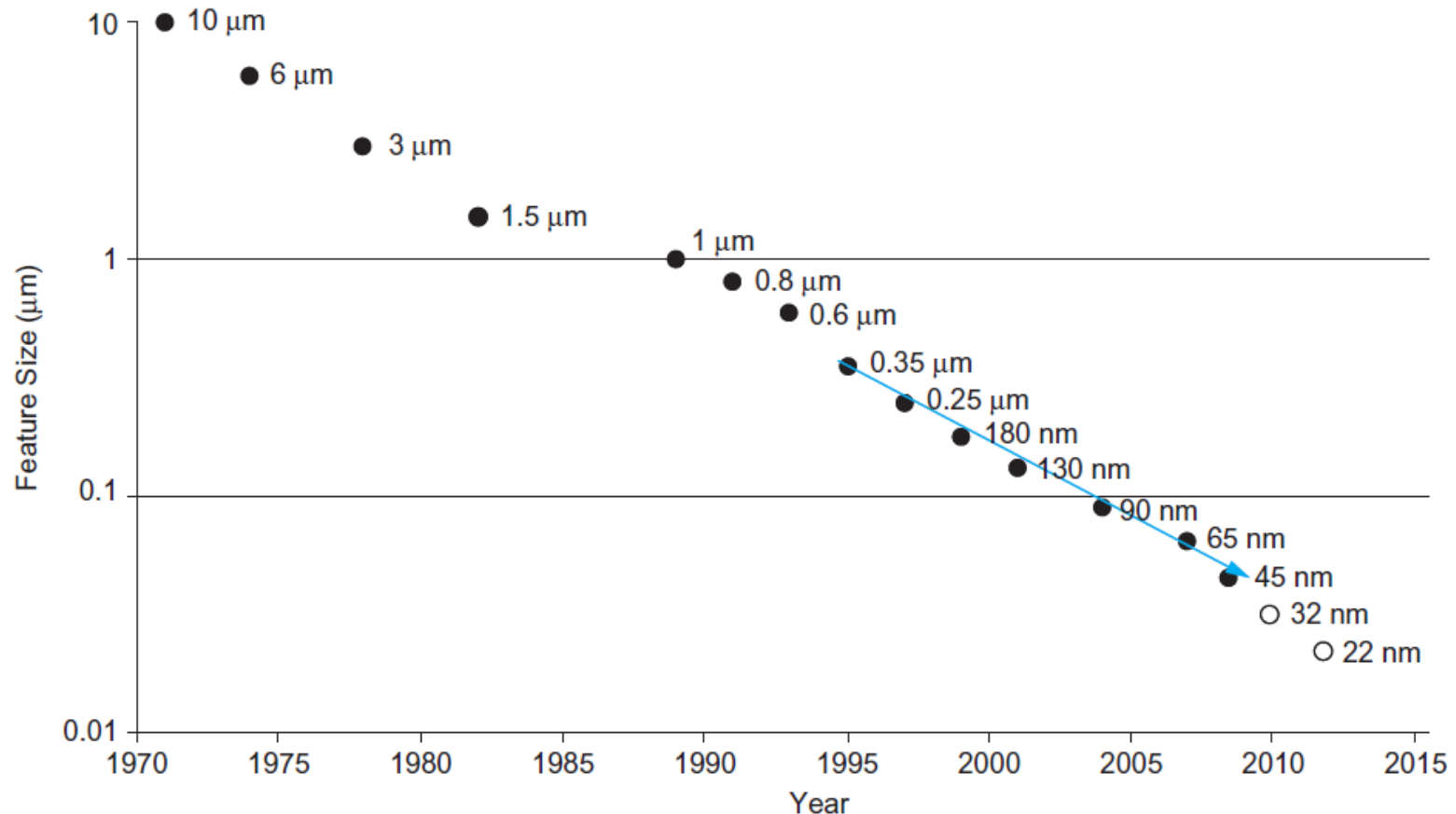
Moore's Law

- ❑ Moore's law [1965]: Transistor count doubles every year
- ❑ Practically: It doubled every 2-3 years since the 4004 [1970s]
- ❑ At the end of the day: It is exponential!



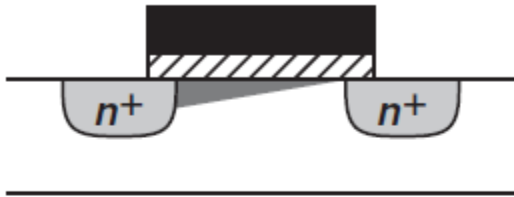
Technology Minimum Feature Size

- ❑ Minimum feature size shrinking 30% ($\approx 1/\sqrt{2}$) every 2-3 years
 - Transistor **area and cost** are reduced by a factor of 2
- ❑ Device scaling brings new challenges in circuit design



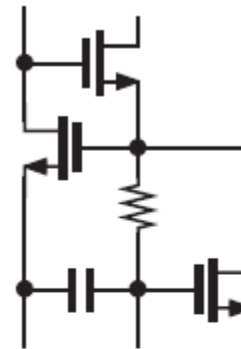
Levels of Abstraction

Device



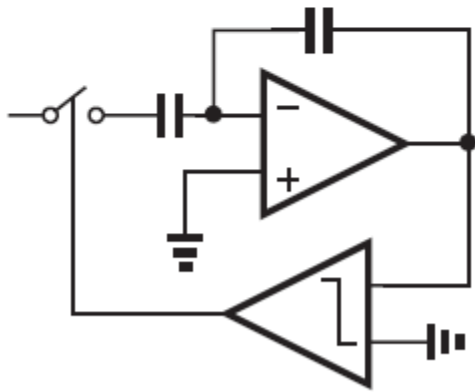
(a)

Circuit



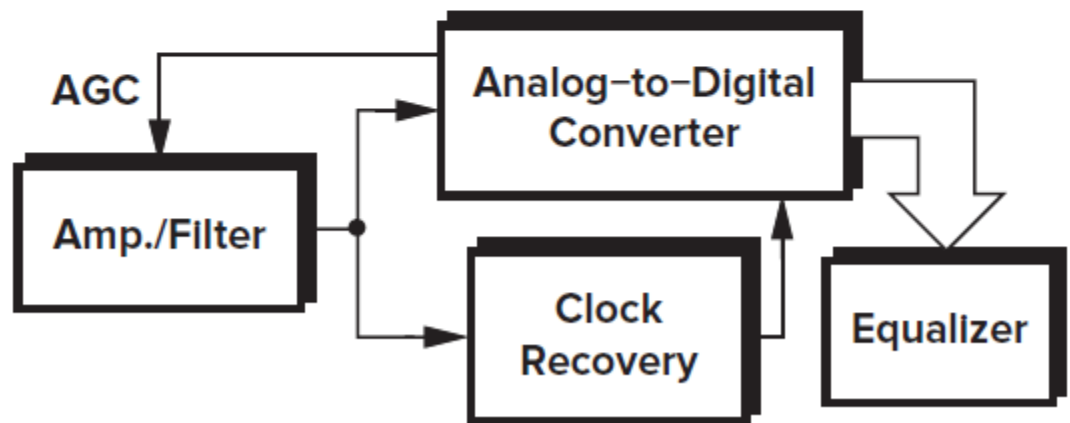
(b)

Architecture



(c)

System



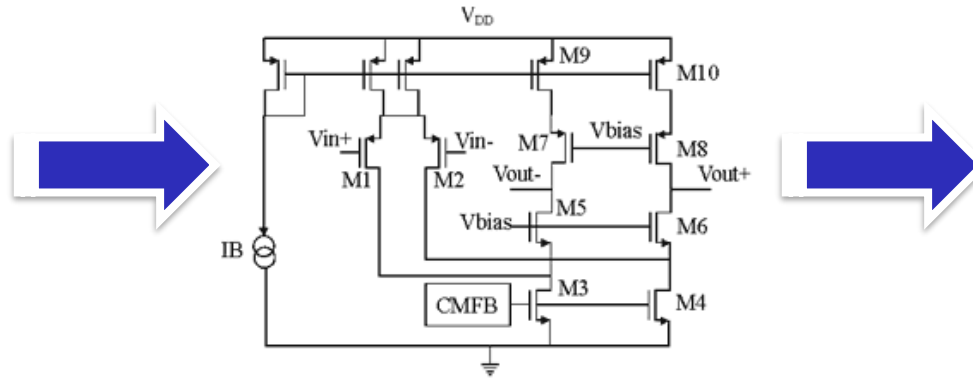
(d)

IC Industry in Egypt



Course Objective

- ❑ To teach the basic knowledge required for:
 - Analog IC analysis and design using CMOS technology
 - Moving from specifications (specs) to block design
 - **Simulating analog ICs using professional CAD tools**



Course Prerequisites

- ❑ You should be familiar with:
 - Analysis of electrical circuits
 - Basic semiconductor physics
 - Basic MOSFET operation and physics
 - MOSFT large signal and small signal models
 - Basic analysis of transistor amplifiers
- ❑ A review will be provided for the above topics
 - But you will struggle if you have never heard about these topics before

References

❑ Textbook

- **B. Razavi**, “Design of analog CMOS integrated circuits,” 2nd ed., McGraw-Hill Ed., 2017.

❑ References for beginners

- **A. Sedra** and **K. Smith**, “Microelectronic circuits,” 7th ed., Oxford University Press, 2015.
- **T. Floyd**, “Electronics Fundamentals, Circuits, Devices, and Applications,” 8th ed., Pearson, 2014.
- **B. Razavi**, “Fundamentals of microelectronics,” 2nd ed., Wiley, 2014.

References

☐ References for professionals

- T. C. **Carusone**, D. **Johns**, and K. W. **Martin**, “Analog integrated circuit design,” 2nd ed., Wiley, 2012.
- P. **Gray**, P. Hurst, S. Lewis, and R. **Meyer**, “Analysis and design of analog integrated circuits,” 5th ed., Wiley, 2009.
- P. **Jespers** and B. **Murmann**, Systematic Design of Analog CMOS Circuits Using Pre-Computed Lookup Tables, Cambridge University Press, 2017.
- D. Stefanovic and M. **Kayal**, Structured Analog CMOS Design Springer, 2008.
- R. J. **Baker**, “CMOS circuit design,” 3rd ed., Wiley, 2010.
- W. **Sansen**, “Analog design essentials,” Springer, 2006.

Canvas

- ❑ Canvas is a learning management system (LMS) used in many universities in the US and around the world
- ❑ We will use Canvas for
 - Posting lectures, notes, etc.
 - Questions and answers
 - Announcements and discussions
 - Quizzes
 - Submitting and grading assignments, reports, etc.
- ❑ **Everyone must register at Canvas today!**

Feedback

- ❑ Don't hesitate to send me feedback to improve the course quality.
- ❑ Avoid two common misconceptions
 1. Feedback should NOT wait to the end of the course!
 - It will be too late to improve anything!
 - But anyway, you may still help next generations 😊
 2. Feedback should NOT be always negative!
 - Too much negative feedback leads to zero output!
 - Too much positive feedback causes oscillation!
 - Be balanced!

What Students Say About this Course

“The training was amazing. It wasn't easy but I enjoyed it. I strongly recommend attending this training for future analog designers.”

“It was an excellent course with a lot of benefits that changed my thinking and understanding towards circuits and analysis ... thanks :)”

“This course is a great experience that you will never have alone.”

“Very great course and very helpful for those who will work in this field in the future.”

“I got a great experience from this course and I applied it practically. My interest in the electronics field became greater than before. I deeply recommend my friends to get it.”

What Students Say About this Course

“One of the greatest courses I have took since I started college.”

“I recommend this course to every student in Communication department.”

“It was definitely a rewarding experience that's worth recommending.”

“I would like to thank you for one of the most important courses that I took so far in college. It has guided my thoughts to continue my career in analog ICs. I really understood and enjoyed everything that I took in this course.”

What Students Say About This Course

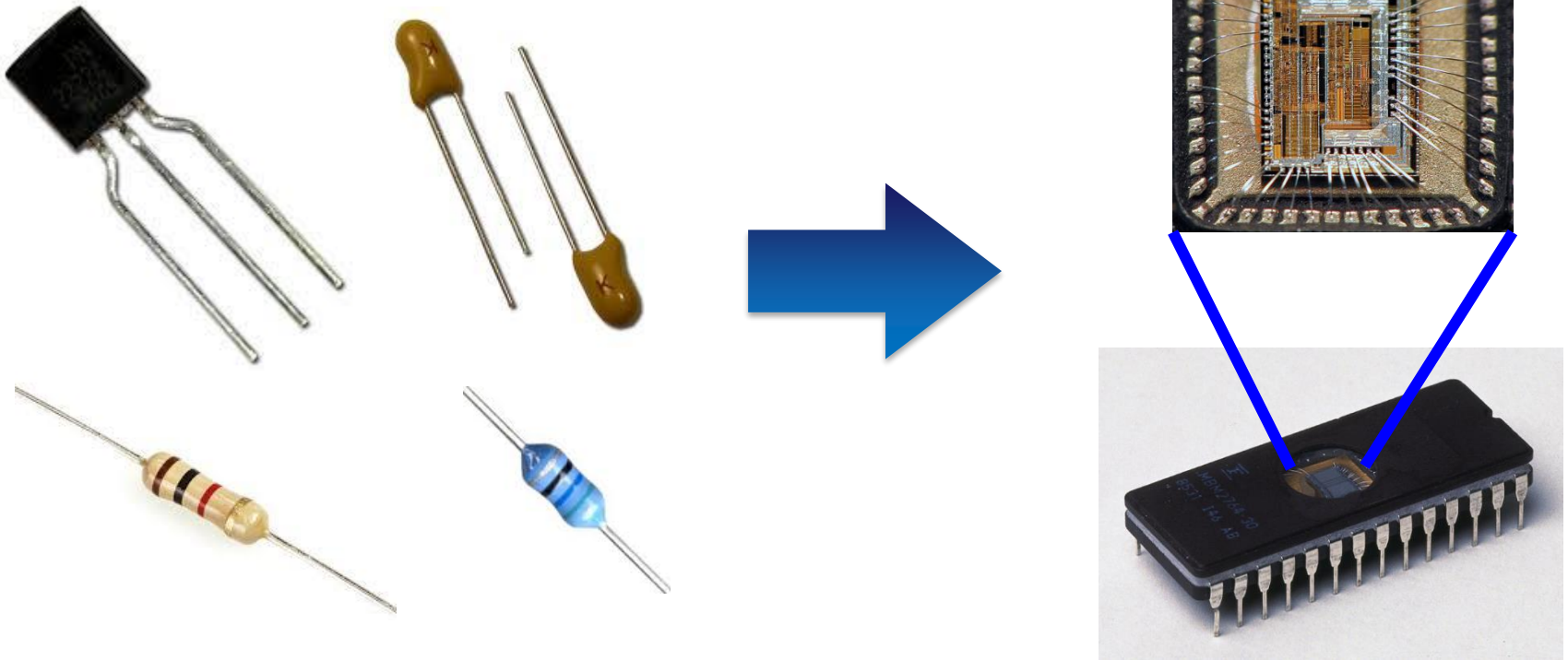
“It was an awesome course . It has a lot of interesting topics, and a lot of knowledge and experience.”

“Amazing mind opener for those interested in electronics.”

“The staff was amazing, and the videos were excellent. The whole course exceeded my expectations. I enjoyed the design and the labs and everything about the course.”

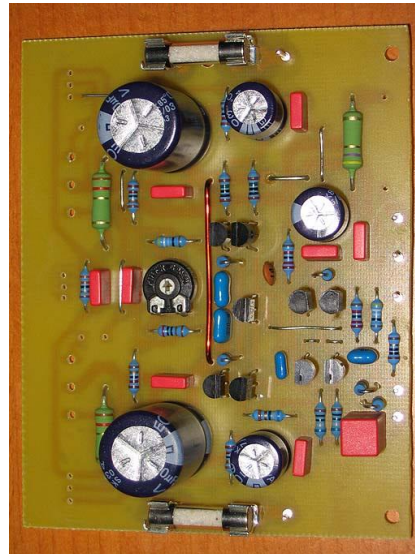
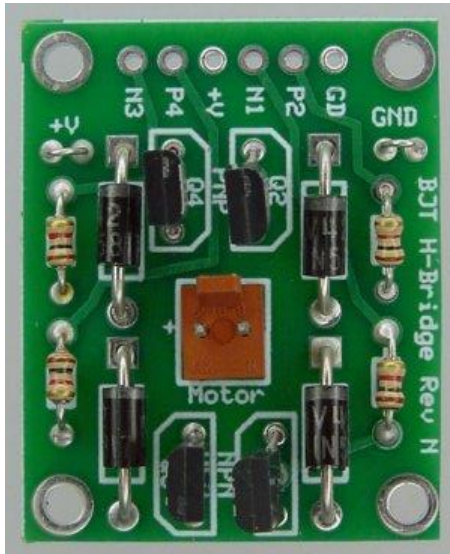
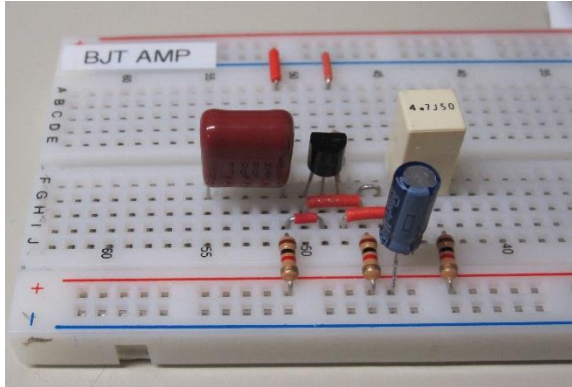
What is an Integrated Circuit (IC)?

- ❑ Various circuit elements: transistors, capacitors, resistors, and even small inductances can be integrated on one chip

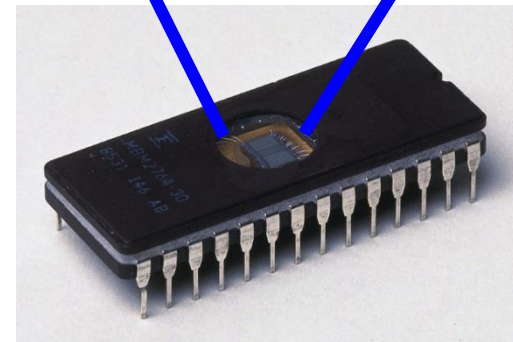
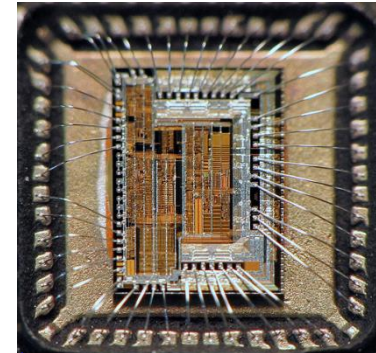


Discrete vs. Integrated Electronics

Circuits using discrete components



Integrated circuit



Integrated Circuit Components

❑ Transistors:

- Billions of tiny transistors can be integrated on the same chip
- Very Large Scale Integration (VLSI): $> 10,000$ transistors

❑ Capacitors:

- Capacitors as large as 100s of pF can be integrated on-chip
- But they consume a lot of chip area → Use sparingly

❑ Resistors:

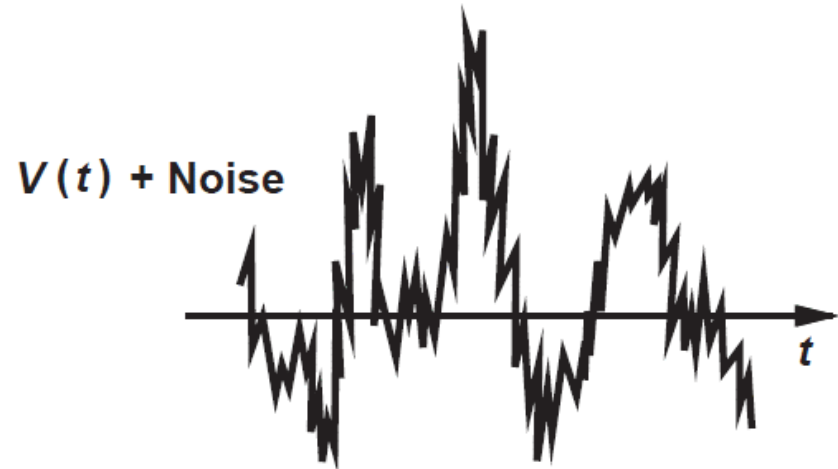
- Resistors as large as few MOhms can be integrated on-chip
- But they consume a lot of chip area → Use sparingly

❑ Inductors:

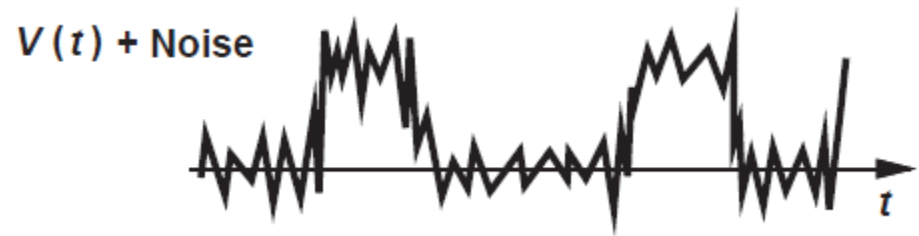
- Small inductors (few nH) can be integrated on-chip
- But they consume a lot of area with relatively poor performance
→ Use sparingly: Only in high frequency circuits (e.g., RFICs)

Analog vs Digital Signals

- ❑ Analog: continuous in time and amplitude



- ❑ Digital: discrete in time and amplitude

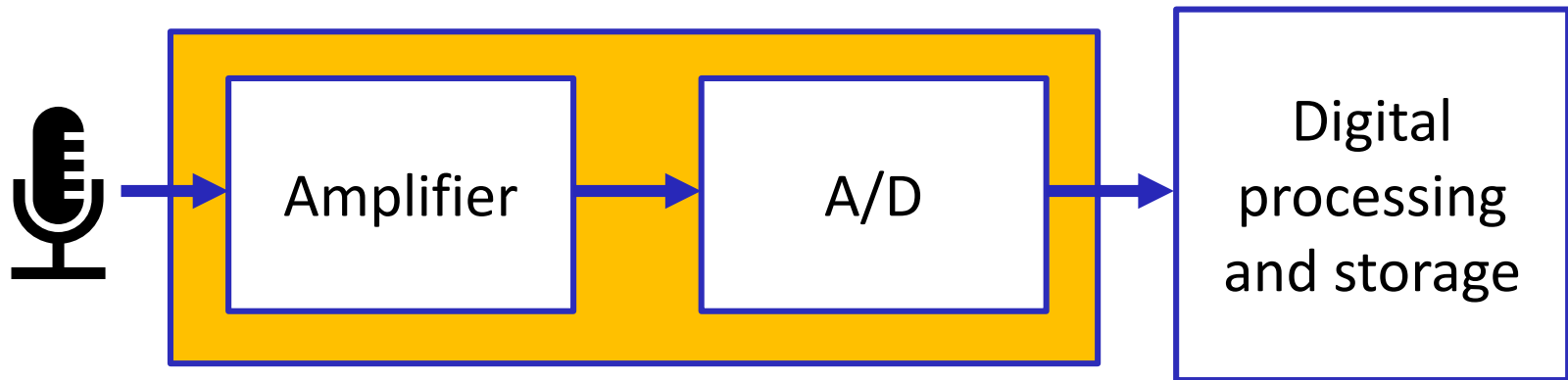


Why Digital?

- ❑ Digital circuits are
 - Less sensitive to noise (robust)
 - Easier to store (digital memories)
 - Easier to process (digital signal processing: DSP)
 - Amenable to automated design
 - Amenable to automated testing
 - Direct beneficiary of Moore's law (down-scaling)

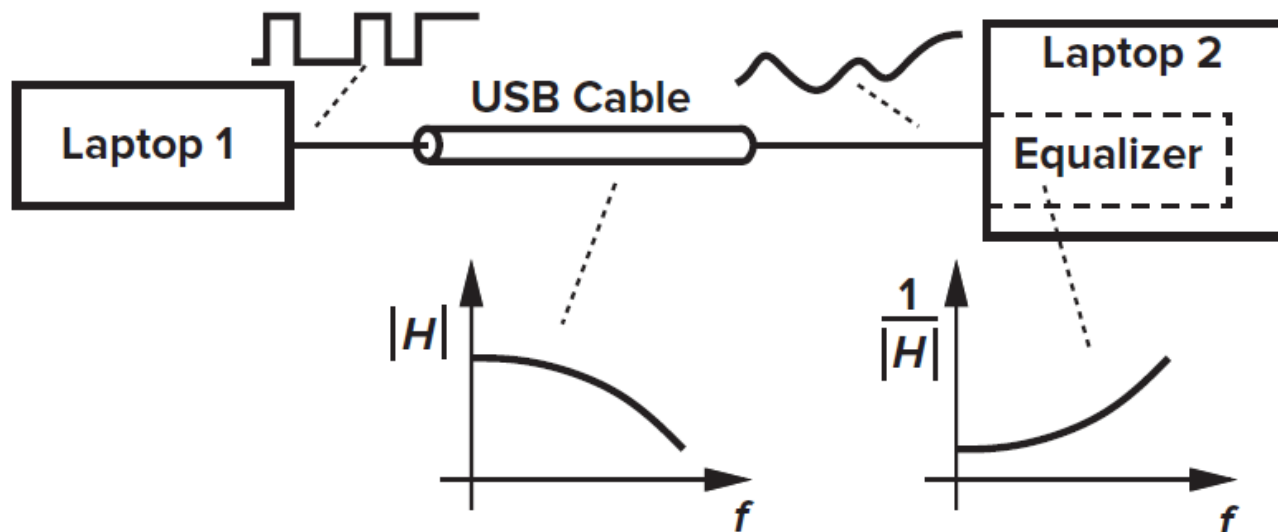
Why Analog?

- ❑ All the physical signals in the world around us are analog
 - Voice, light, temperature, pressure, etc.
- ❑ We (will) always need an “analog” interface circuit to connect between our physical world and our digital electronics



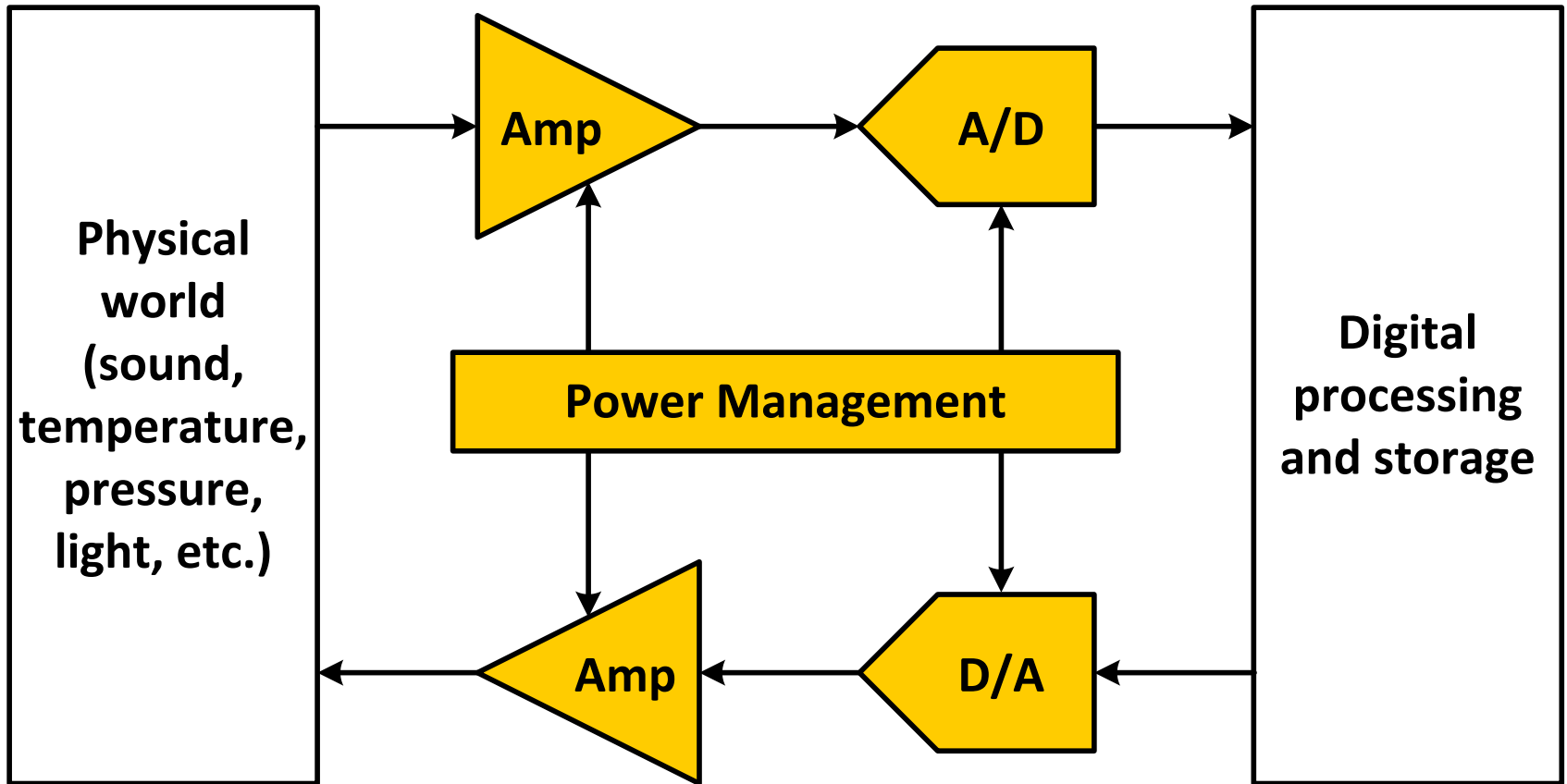
Why Analog?

- ❑ High speed digital design is actually analog design!
- ❑ At low speeds, we may directly digitize the signal and perform the signal processing in the digital domain.
- ❑ At high speeds, signal processing in the analog domain is much more energy efficient.
- ❑ The boundary between high and low speed has risen over time.



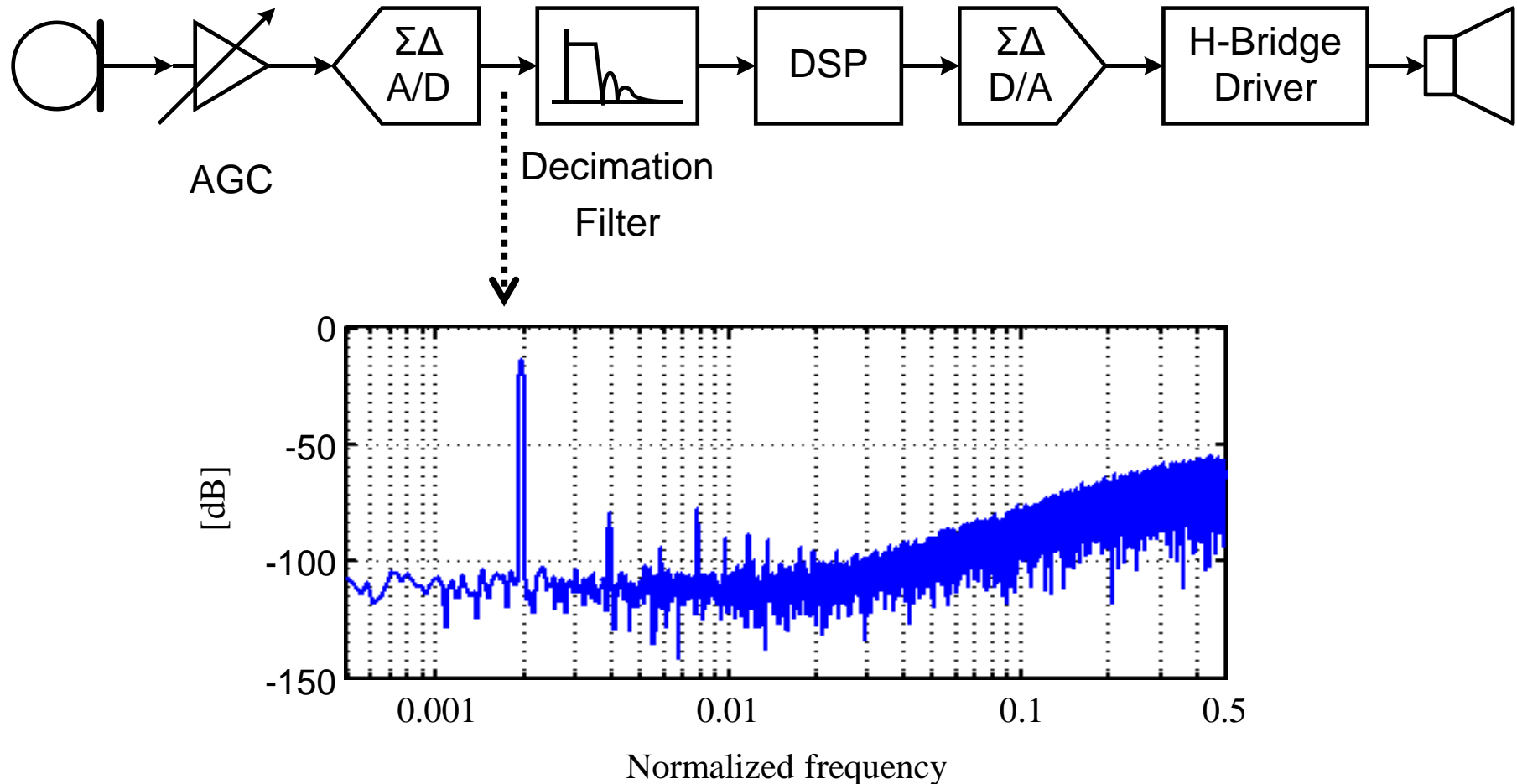
Signal Processing Chain

- There will always be jobs for analog/mixed-signal/RF designers ☺



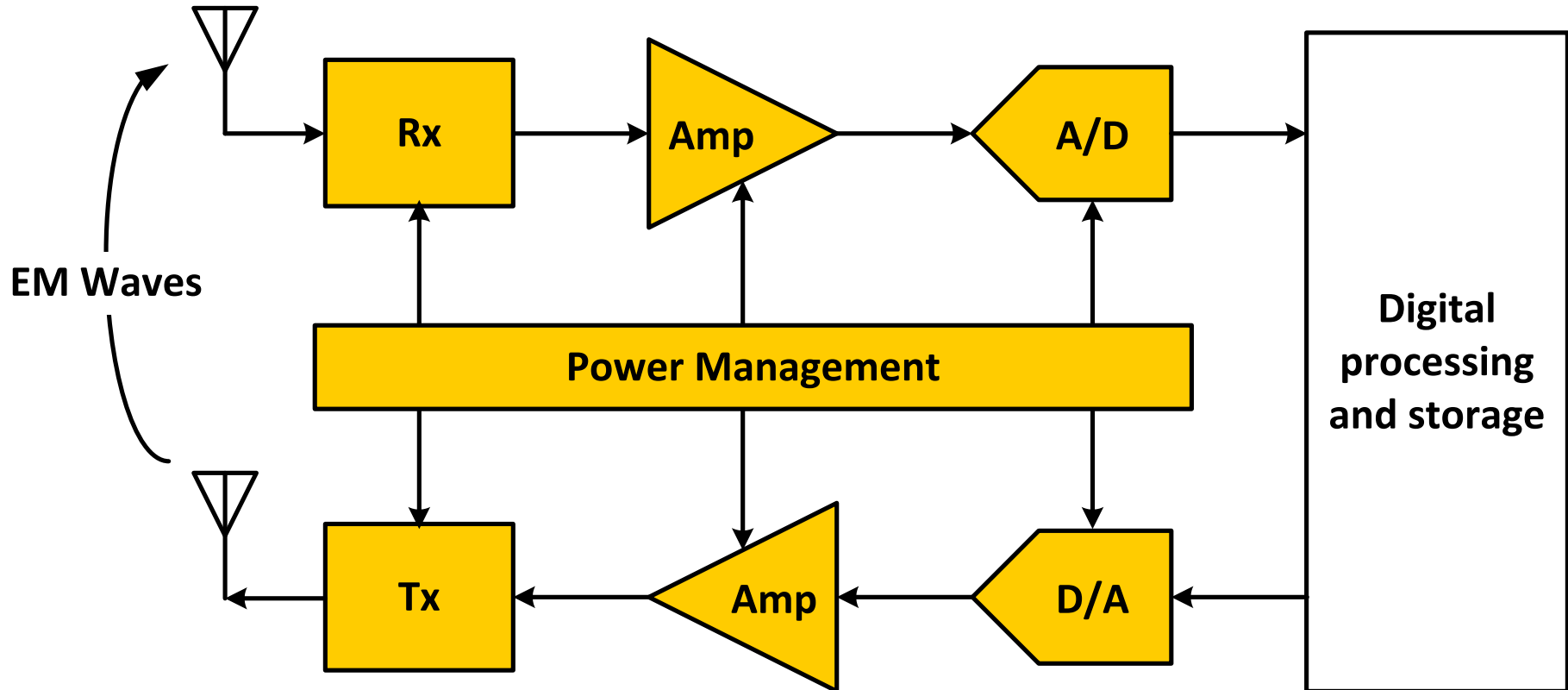
Example: Mixed-Signal Hearing Aid

- There will always be jobs for analog/mixed-signal/RF designers ☺



Wireless Signal Processing Chain

- There will always be jobs for analog/mixed-signal/RF designers ☺



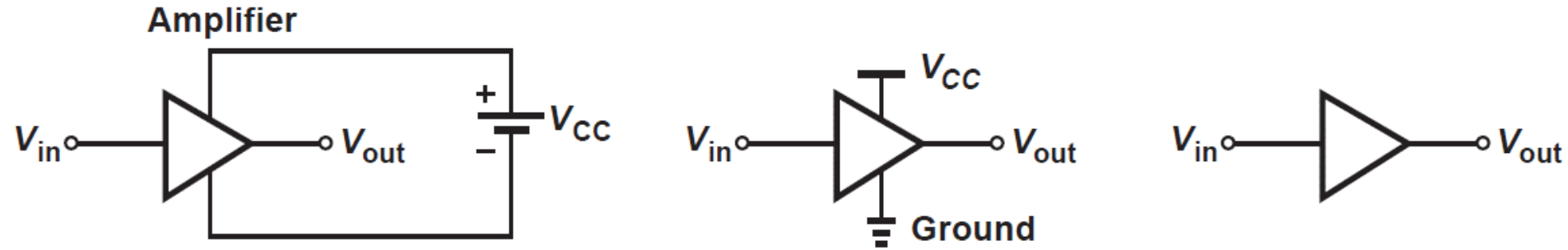
Why CMOS?

- ❑ Early integrated circuits primarily used bipolar transistors (BJTs)
- ❑ CMOS technologies dominated the digital market since the 1980s
 - CMOS = Complementary MOS = NMOS + PMOS
 - 1. Consumed negligible static power
 - Was indeed negligible in the past
 - But not negligible any more...
 - 2. Required very few devices per gate
 - 3. Can be scaled down more easily
 - 4. Lower fabrication cost
- ❑ For analog design, BJTs used to be much better than MOSFETs
 - Faster, less noisy, less variations, more energy efficient
- ❑ Then why analog CMOS?

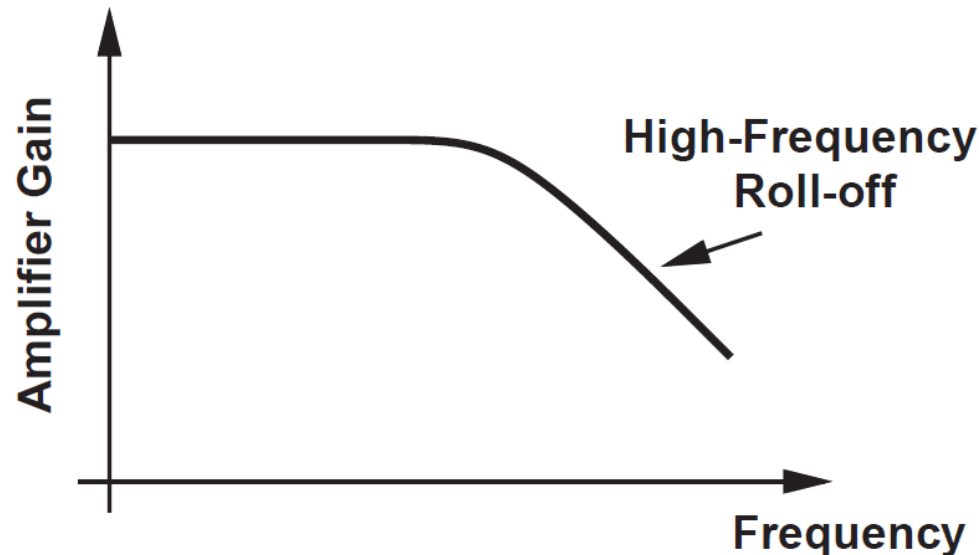
Why Analog CMOS?

- ❑ ICs market is driven primarily by memories and microprocessors
 - The analog designer needs to survive in a digital driven market
- ❑ We want to integrate analog and digital on the same chip
 - Mixed-signal design and system-on-a-chip
- ❑ BJTs used to be faster, but with continuous scaling, MOSFET speed exceeded BJT
- ❑ MOSFET can operate with lower supply voltage

Analog Amplifier



- ❑ The amplifier has finite gain ($A_v = \frac{v_{out}}{v_{in}}$) and finite bandwidth (speed)

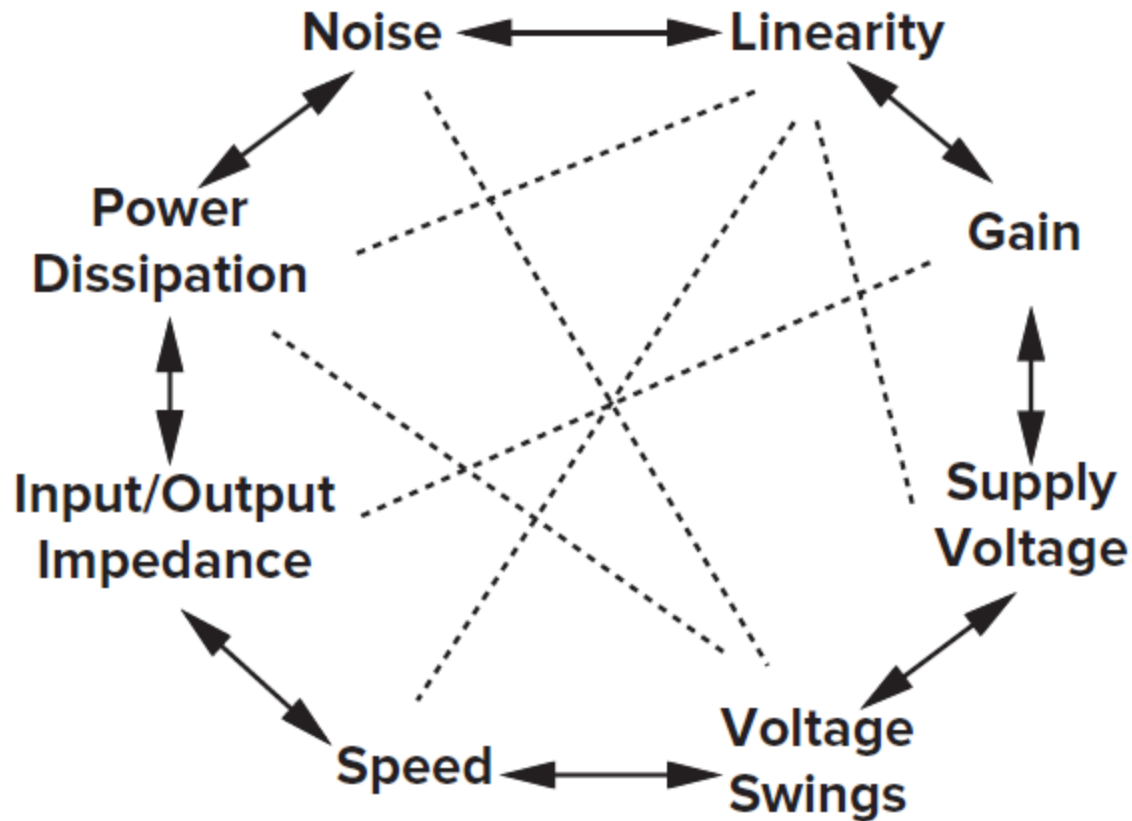


Analog Design Challenges

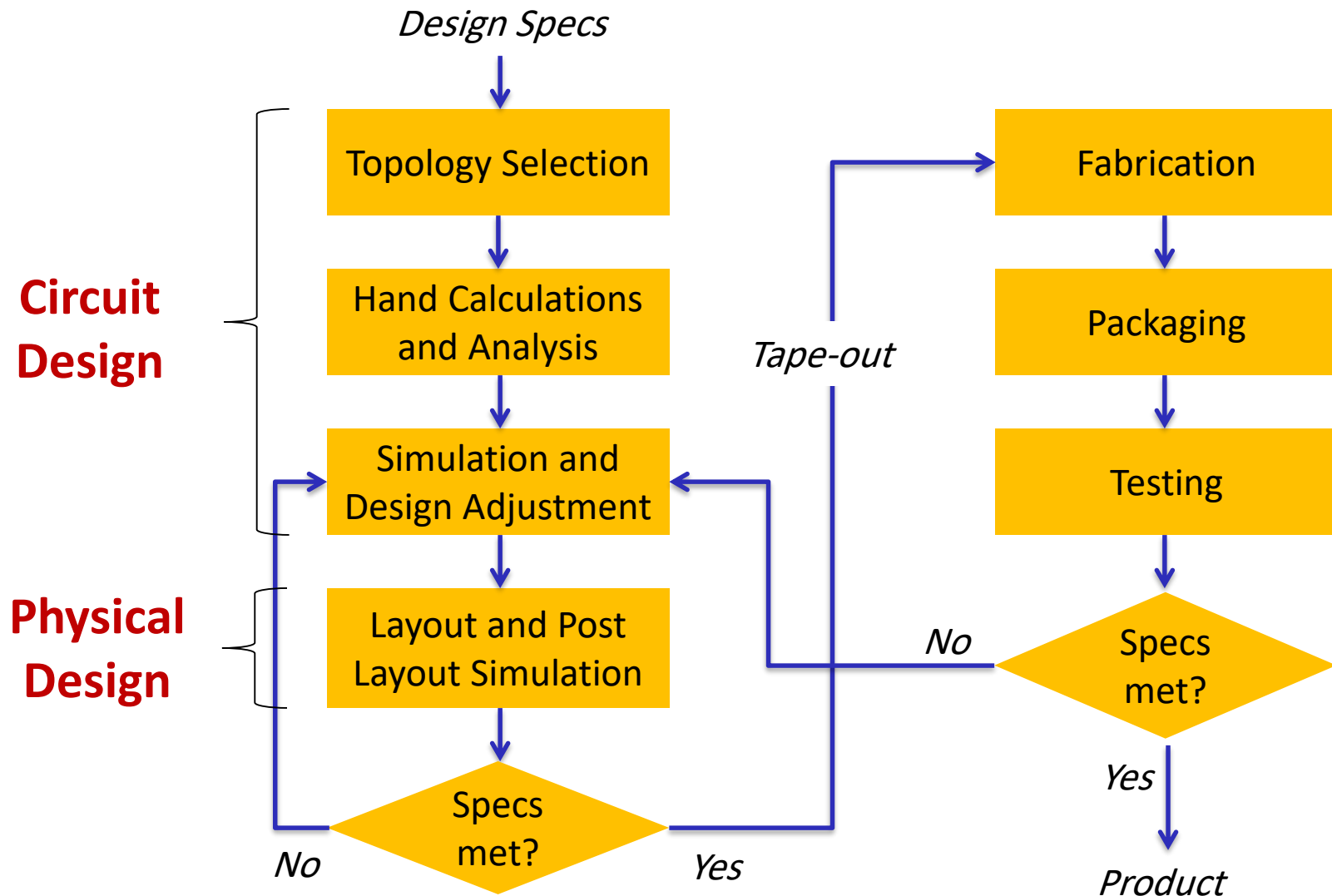
- ❑ Device scaling
 - Transistors become faster, but the gain declines
- ❑ Supply voltage scaling
 - From 12V in 1970s to less than 1V nowadays
- ❑ Low power consumption
 - Increase battery lifetime, decrease cost and heat emissions
- ❑ Complexity
 - Continuous increase in transistor count and system complexity
- ❑ PVT variations
 - Tolerate large process, voltage, and temperature variations
- ❑ New applications
 - Wireless standards, wearables, IoT, serial links (e.g., USB), ...

Analog Design Challenges

- ❑ Analog design automation is a difficult task

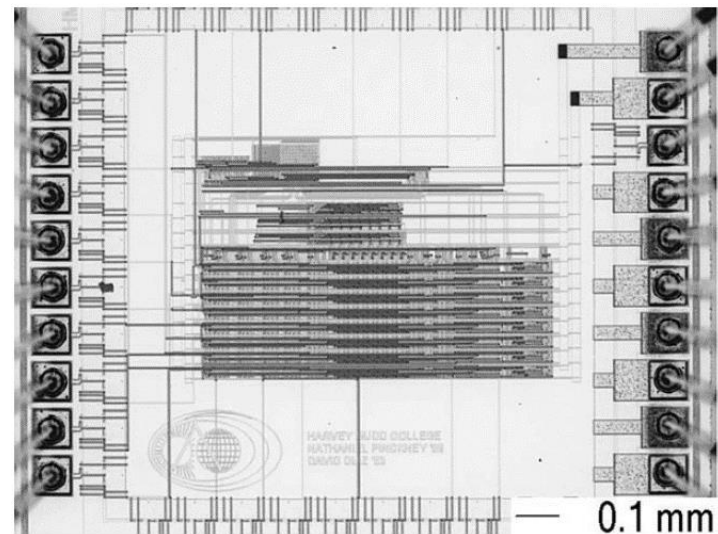
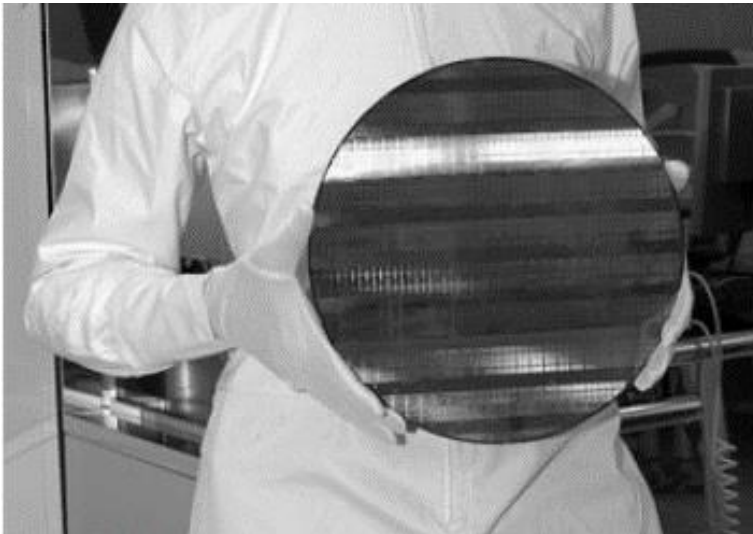


Analog IC Design Flow (Simplified)



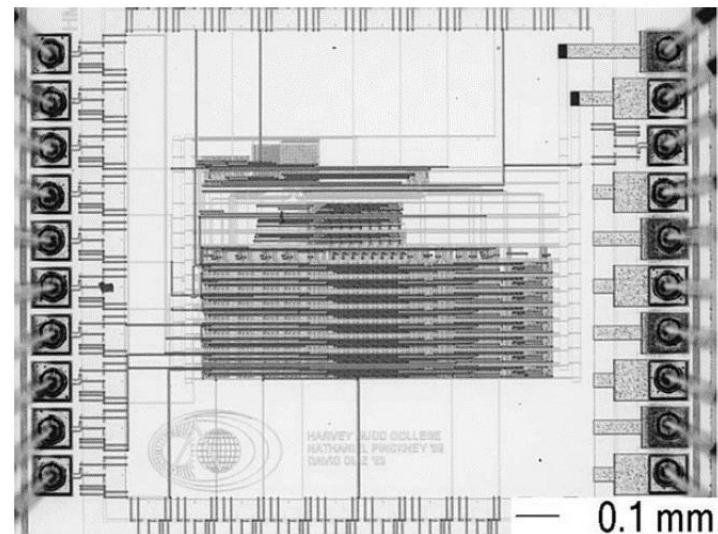
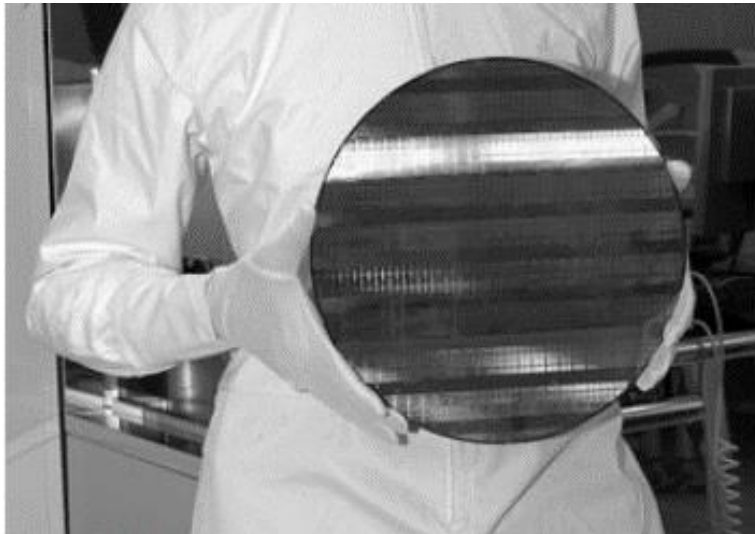
Tape-Out

- ❑ The layout is sent to the fab in a format called GDS II
 - Previously it was sent on a magnetic tape → tape-out
 - Now by email (small design) or FTP (large design)



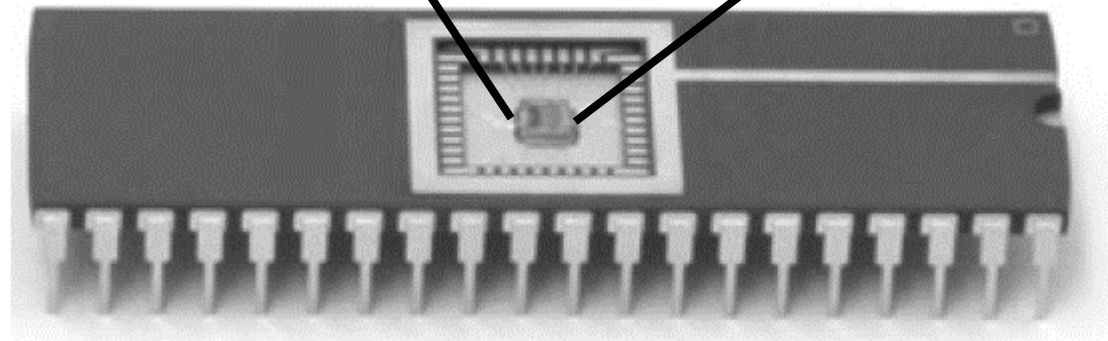
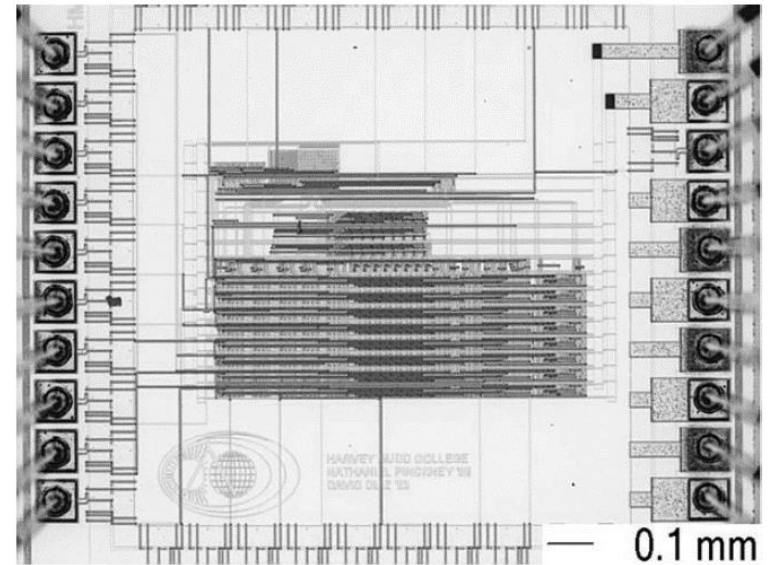
Tape-Out

- ❑ ICs are fabricated on silicon wafers
 - Turnaround time ~ 3months
- ❑ A fabrication run in 65nm process costs about \$3 million
 - Cost sharing using MPW (multi-project wafer)
 - US: MOSIS
 - Europe and MENA: Europractice



Packaging and Testing

- ❑ Wafer diced into dies
- ❑ Gold bond wires from die I/O pads to package
- ❑ Packaging is now much more advanced than the simple DIP
→ DIP: Dual inline package



References

- ❑ A. Sedra and K. Smith, “Microelectronic Circuits,” Oxford University Press, 7th ed., 2015
- ❑ B. Razavi, “Fundamentals of Microelectronics,” Wiley, 2nd ed., 2014
- ❑ B. Razavi, “Design of Analog CMOS Integrated Circuits,” McGraw-Hill, 2nd ed., 2017
- ❑ N. Weste and D. Harris, “CMOS VLSI Design,” Pearson, 4th ed., 2010

Thank you!

Modern “Moore” Concepts

❑ More Moore

- Further miniaturization of transistor as per Moore’s law
- New materials for performance enhancement (HK, SOI, III-V)
- We are approaching the “physical limits” of the transistor

❑ More than Moore

- Adding functionalities **not** associated with transistor scaling to increase device value (sensors, MEMS, bio, passives, etc.)
- 3D integrated circuits

❑ Beyond Moore (Beyond CMOS)

- Exploring new device architectures
- Gate-all-around transistors, nanowires (NW-FET), nanotubes (CNT), memristors, spin electronics, graphene, etc.

IC Technology Generations

- ❑ Early integrated circuits primarily used bipolar transistors (BJTs)
- ❑ 1960s: MOS ICs became attractive for their low cost
 - MOS transistor occupied less area
 - The fabrication process was simpler
 - Early commercial processes used only PMOS transistors and suffered from poor performance, yield, and reliability
- ❑ 1970s: Processes using only NMOS transistors became common
- ❑ Digital circuits in all the previous technologies have quiescent power
 - Power is dissipated when the circuit is idle, i.e., not switching
 - This limits the maximum number of transistors that can be integrated on one die

IC Technology Generations (Cont'd)

- ❑ 1980s: The VLSI era
 - Power consumption became a major issue
 - CMOS processes were widely adopted and replaced NMOS and bipolar processes for nearly all digital logic applications
 - CMOS = Complementary MOS = NMOS + PMOS
 - A key advantage for “digital” CMOS is that it has negligible idle (static) power consumption
- ❑ Nowadays:
 - With aggressive scaling and billions of transistors, CMOS idle leakage current is not negligible any more
 - But no better technology is available yet...

How to Design a Billion Transistor Chip?

1. Abstraction

- Hiding details until they become necessary

2. Structured design

- Hierarchy: Block, sub-blocks, ... → Tree structure (from root to leaf cells)
- Regularity: Min no. of different blocks → Block reuse (e.g., standard cells)
- Modularity: Blocks are black boxes that have well-defined interfaces → Combine to build larger system without surprises!

3. CAD Tools

- Automation, automation, automation!
- Analog automation is way behind digital automation

CAD/EDA

❑ Analog design

- Design entry (schematic), simulation, layout
- Verification (LVS: layout vs schematic, DRC: layout design rule check, parasitic extraction, post-layout simulation)

❑ Digital design

- Design entry (e.g., HDL) and simulation
- Automated synthesis (from HDL to gates)
- Automated place and route (from gates to transistor layout)
- Verification

❑ System design

- Behavioral modeling and high level simulation/verification

❑ EM simulation, process simulation, device simulation, etc.